

### ISE4043 REV E2 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
IPC B1	1		ISE4043	Any	Printed Circuit Board	
C1, C6	2	0.1uF	C1005X5R1A104K	TDK	CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	0402
C2	1	10uF	C0603C106M9PACTU	Kemet	CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0603	0603
C3, C10	2	1uF	C1005X5R1A105K050BB	TDK	CAP, CERM, 1 µF, 10 V, +/- 10%, X5R, 0402	0402
C4	1	0.01uF	GRM155R60J103KA01D	MuRata	CAP, CERM, 0.01 µF, 6.3 V, +/- 10%, X5R, 0402	0402
C5	1	4.7uF	C1005X5R1A475K050BC	TDK	CAP, CERM, 4.7 µF, 10 V, +/- 10%, X5R, 0402	0402
C7	1	1000pF	GRM155R61A102KA01D	MuRata	CAP, CERM, 1000 pF, 10 V, +/- 10%, X5R, 0402	0402
C8	1	2200pF	GRM155R60J222KA01D	MuRata	CAP, CERM, 2200 pF, 6.3 V, +/- 10%, X5R, 0402	0402
C9	1	0.015uF	GRM155R71C153KA01D	MuRata	CAP, CERM, 0.015 µF, 16 V, +/- 10%, X7R, 0402	0402
C11	1	0.01uF	GRM155R61A103KA01D	MuRata	CAP, CERM, 0.01 µF, 10 V, +/- 10%, X5R, 0402	0402
C13	1	0.1uF	C1005X5R0J104K	TDK	CAP, CERM, 0.1 µF, 6.3 V, +/- 10%, X5R, 0402	0402
C14	1	1.8uF	C0805C185K8PACTU	Kemet	CAP, CERM, 1.8 µF, 10 V, +/- 10%, X5R, 0805	0805
C15	1	0.18uF	GRM155R60J184KE01D	MuRata	CAP, CERM, 0.18 µF, 6.3 V, +/- 10%, X5R, 0402	0402
J1	1		S5B-ZR-SM4A-TF(LF)(SN)	JST Manufacturing	Header(Shrouded), 1.5mm, 5x1, Tin, R/A, TH	Header(Shrouded), 1.5mm, 5x1, R/A, TH
Q1	1	30 V	BC849CLT1G	ON Semiconductor	Transistor, NPN, 30 V, 0.1 A, SOT-23	SOT-23
R1, R2	2	0	ERJ-8GEY0R00V	Panasonic	RES, 0, 5%, 0.25 W, 1206	1206
R3, R4	2	100k	RC1005F104CS	Samsung Electro-Mechanics	RES, 100 k, 1%, 0.063 W, 0402	0402
R5, R6	2	392k	CRCW0402392KFKED	Vishay-Dale	RES, 392 k, 1%, 0.063 W, 0402	0402
R7, R10	2	10.0Meg	CRCW040210M0FKED	Vishay-Dale	RES, 10.0 M, 1%, 0.063 W, 0402	0402
R11, R12	2	200k	CRCW0402200KFKED	Vishay-Dale	RES, 200 k, 1%, 0.063 W, 0402	0402
R13, R14	2	3.92k	CRCW04023K92FKED	Vishay-Dale	RES, 3.92 k, 1%, 0.063 W, 0402	0402
R15	1	1K ohm	EVM-3YSX50B13	Panasonic	TRIMMER, 1K Ohm, 0.15W, SMD	3.1x3.45mm
R16, R17	2	10K ohm	EVM-3YSX50B14	Panasonic	TRIMMER, 10K Ohm, 0.15W, SMD	3.1x3.45mm
R18	1	1.00k	ERJ-2RKF1001X	Panasonic	RES, 1.00 k, 1%, 0.1 W, 0402	0402
RC1	1	0	ERJ-2GE0R00X	Panasonic	RES, 0, 5%, 0.063 W, 0402	0402
U1	1		OPA320AIDBVT	Texas Instruments	Precision, 20 MHz, 0.9 pA Ib, RRIO, CMOS Operational Amplifier, 1.8 to 5.5 V, -40 to 125 degC, 5-pin SOT23 (DBV0005A), Green (RoHS & no Sb/Br)	DBV0005A
U2, U4	2		OPA2320AIDGKT	Texas Instruments	Precision, 20 MHz, 0.9 pA Ib, RRIO, CMOS Operational Amplifier, 1.8 to 5.5 V, -40 to 125 degC, 8-pin SOP (DGK0008A), Green (RoHS & no Sb/Br)	DGK0008A
U3	1		INA132UA/2K5	Texas Instruments	Low Power, Single-Supply DIFFERENCE AMPLIFIER, D0008A	D0008A
C12, C16	0	4.7uF	GRM155R60J475ME87D	MuRata	CAP, CERM, 4.7 µF, 6.3 V, +/- 20%, X5R, 0402	0402
D1	0	Photodiode	Customer Option	Customer Option	Photodiode	T-1 3/4 LED, TH
D2	0	IR LED	Customer Option	Customer Option	IR LED	T-1 3/4 LED, TH
FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
RC2	0	0	ERJ-2GE0R00X	Panasonic	RES, 0, 5%, 0.063 W, 0402	0402

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